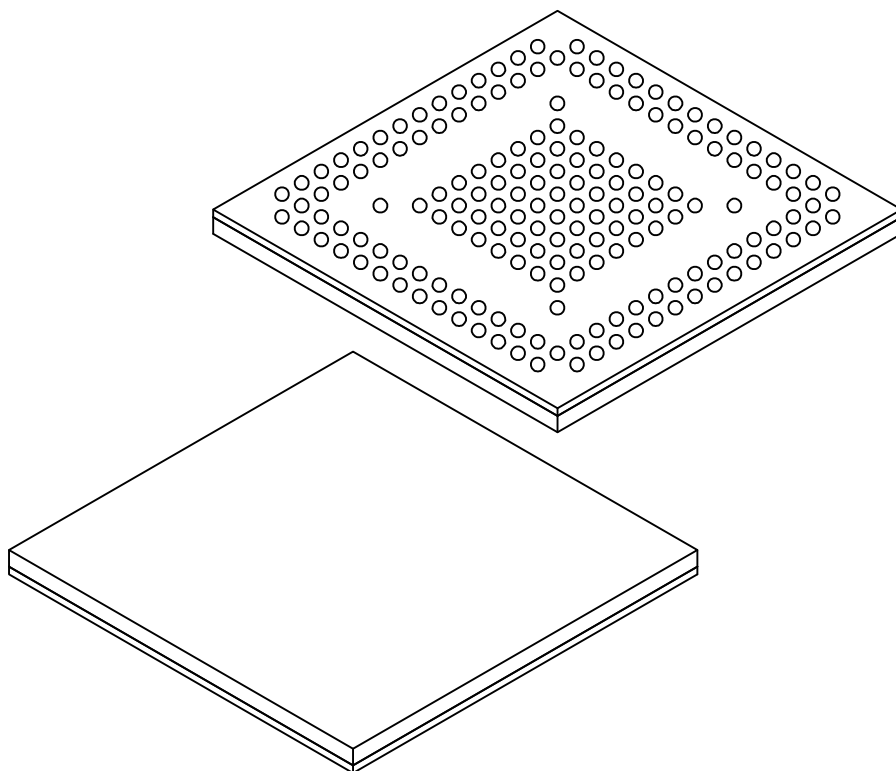


176-Ball Thin Fine-Pitch Ball Grid Array (5MX) - 14x14x1.19 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
		Dimension Limits	MIN	NOM	MAX
Number of Terminals	N		176		
Pitch	e		0.80 BSC		
Overall Height	A	-	-	1.19	
Ball Height	A1	0.21	0.30	-	
Mold Thickness	A2	0.48	0.53	0.58	
Overall Length	D	14.00 BSC			
Overall Width	E	14.00 BSC			
Ball Diameter	b	0.35	0.40	0.45	

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 REF: Reference Dimension, usually without tolerance, for information purposes only.